

第七届热管理产业大会暨博览会

The 7th Thermal Management Industry Conference and Exposition

招展函

Letter of Invitation

2026年12月2-4日

December 2-4, 2026

深圳国际会展中心（宝安）

Shenzhen World Exhibition & Convention Center

传递多一点

A LITTLE MORE TRANSFER



参展邀请 INVITATION

电子器件、芯片和设备等持续向微型化、高性能化、集成化及多功能等方向发展，功率密度和发热量急剧攀高。在新质生产力发展背景下，消费电子、电力电子、人工智能、5G、数据中心、物联网、动力电池、电动车、储能、新能源、绿色建筑等应用领域场景的技术迭代和节能环保需求，都积极推动了高效的热管理创新性技术解决方案的发展，以保证终端产品的效率、可靠性、安全性、耐用性和持续稳定性。

The devices, chips and electronic equipments are developing towards to miniaturization, high performance, integration and multi-functions, the power density and calorific value rise sharply. Under the new quality productive forces, the technology iteration and energy conservation and environmental protection needs of Consumer Electronics, Power Electronics, Artificial Intelligence, 5G, Data Centers, Internet of Things, Power Batteries, Electric Vehicle, Energy Storage, New Energy, Green Buildings and other application scenarios. These demands are actively driving the development of innovative technical solutions for efficient thermal management to ensure the efficiency, reliability, safety, durability and continued stability of end products.

第七届热管理产业大会暨博览会的举办，将高效呈现热管理产业链的一站式价值对接平台，以满足和促进热管理行业各单位交流、合作和共赢发展。创新型材料、仪器、设备、设计与仿真、解决方案、专利技术、应用场景等荟聚链接和呈现将是博览会的重要组成部分；热管理领域科学、材料、技术和工程等相关专题论坛、圆桌讨论、闭门研讨会、创新创业项目展示、新品发布、需求对接等活动也将精彩同期呈现，特别是科研单位创新性的技术和成果也将获得从实验室对接转移到市场的机会。

The 7th Thermal Management Industry Conference & EXPO in 2025, is an opportunity to promote communication, cooperation and win-win development between each organization in the thermal management industry. The EXPO will effectively present a one-stop value matching platform for the thermal management industry chain. Connections and presentations of innovative material products, instruments, equipments, design and simulation, solutions, patent technology and application scenarios will be the important part of this EXPO. There will also be theme forums, Roundtable, Workshop, innovation and entrepreneurship project display, new product release, demand docking and other wonderful activities related to science, materials, technology and engineering in the thermal management field. In particular, the innovative research findings and achievements of scientific research institutes will also have the opportunity to transfer from the laboratory to the market.

展会信息

Exhibition Information

展会名称：第七届热管理产业大会暨博览会（iTherM2026）

The 7th Thermal Management Industry Conference and Exposition

展会时间：2026年12月2-4日

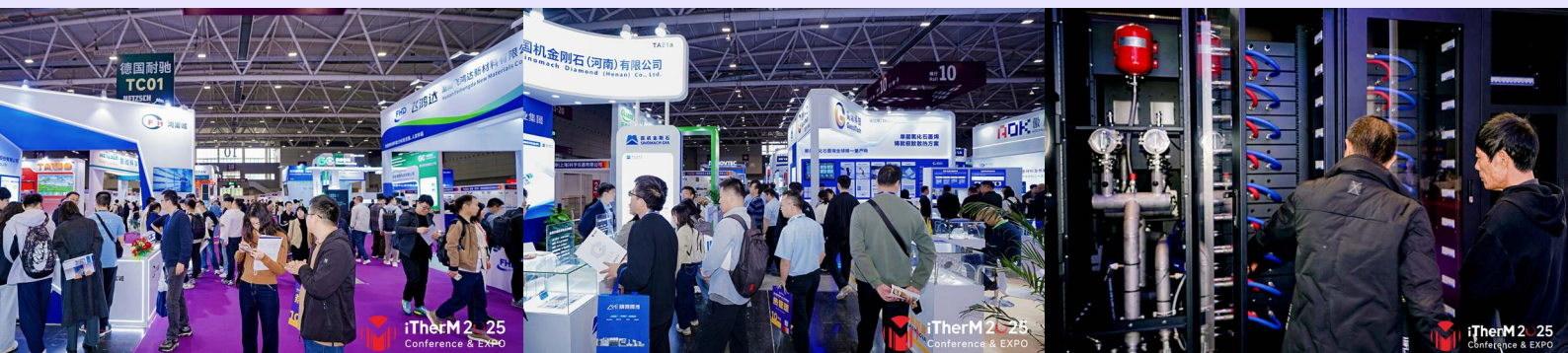
TIME: December 2-4, 2026

展会地点：深圳国际会展中心（宝安）

VENUE: shenzhen World Exhibition & Convention Center

主办单位：宁波德泰中研信息科技有限公司

HOSTS: NingBo DT Information & Technology Co., Ltd.



展览面积 SCALE of EXHIBITION

20,000 m²

参展企业 EXHIBITORS

300+

行业观众 VISITORS

28,000+

同期活动 ACTIVITIES

20+

参展您将收获 WHAT YOU CAN GAIN

1. 行业产业链资源整合，与超过70%的专业观众建立有效业务联系。
2. 把握和洞见未来发展趋势，创造极佳的商务及技术分享互动，收获广阔的商业机会。
1. Integrate the Industry chain resources, build effective business connections with more than 70% professional visitors.
2. Gain insight into future development trends, have the excellent business and technology sharing interaction experience, gain a wide range of business opportunities.

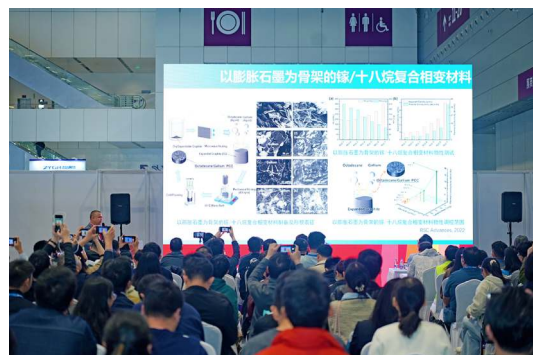
把握前沿动态、洞见发展趋势。诚挚邀请热管理产业链企业、专业采购商、专业观众等各界人士参展参会，共享发展机遇。

Seizing the cutting-edge dynamic, having insight into the development trend. We sincerely invite the high-quality enterprises in the thermal management industry, professional purchasers, professional visitors and others from all walks of life to participate in this exposition and share development opportunities.

iTherM2025回顾

REVIEW of THE iTherM2025

展览面积 Exhibition Area	演讲报告 Lectures	媒体曝光 Scale of Exhibition	参会人员 Conference Participants
15,000 m ²	130+	100w+	2,000+
参展企业 Exhibitors	行业观众 Visitors	企业&机构 Enterprise & Organization	专题活动 Theme Events
180+	23,000+	800+	20+



↑ iTherM2025现场照片 (2025年12月3-5日, 深圳国际会展中心)

为什么参与

OPPORTUNITIES of iTherM2026

精准邀请专业采购商 Invite Professional Purchasers Accurately

邀请行业内大型、专精特新、中小企业及产业园区等采购商和参观团参加供需对接、项目路演和同期活动，促成参展企业和采购商实现精准对接。

Invite large, specialized new, small and medium-sized enterprises, industrial parks and other purchasers and visiting groups to participate in the supply-demand meetings, project roadshows and concurrent activities, so as to achieve accurate matchmaking between exhibitors and purchasers.

传递多一点

A LITTLE MORE TRANSFER

全年活动精彩纷呈 Wonderful Activities Throughout The Year

全年供需对接、项目&招商路演、政策解读、对接签约、投融资推介、视频会议等多场景预热活动，专业性和实效性进一步提升和扩大。

Hold pre-exhibition warm-up activities, supply-demand matching, projects & investment roadshows, policy interpretation, cooperation sign-up, investment and financing promotion, video conferences and other multi-scene activities, further enhance and expand the professionalism and effectiveness.

搭建产业链企业沟通平台 Build A Communication Platform For Enterprises In Thermal Management Industry

组织开展企业、科研院所等单位之间的论坛对话活动，共同探讨行业创新发展愿景和产业趋势，传递业界声音。同时提升参展便利化水平并提供优质服务保障，吸引带动更多企业参展参观。

Organize and carry out forum dialogue activities between enterprises, scientific research institutes and other organizations. Jointly discuss the industry innovation vision and industrial trend, actively make proposals and help the industry to express. At the same time, enhance the level of facilitation and provide high-quality services to attract more enterprises to visit the exposition.

传递多一点

A LITTLE MORE TRANSFER

加大品牌宣传力度 Strengthen Brand Publicity

融合新媒体、短视频、电视和广播等多视角资源，全方位呈现热管理材料技术行业盛会，凸显影响力、传播力和引领力。

Activities will attract the attention and reports of a number of professional and mass media, improve the brand exposure, expand enterprise influence. Integrates new media, short video, TV and radio to present the grand event of thermal management materials technology industry in an all-round way, and will strengthen the influence, penetration, guidance.

新产品新技术首发平台 A Stage for New Product and Technology Debut

荟聚高新技术企业精心发布新产品新技术新服务，展示最新产业成果、汇聚前沿领先技术。搭建初创科技企业与创投机构的交流平台，增强活动对科技初创企业成长的服务功能。

Gather high-tech enterprises to release new products, new technology and new services, display the latest industrial achievements and gather the leading technology. Build a platform for communications between technology start-ups and venture capital institutions, to enhance the service function of the conference for the growth of technology start-ups.

传递多一点

A LITTLE MORE TRANSFER

多维度定向推广和邀约 Multi-dimensional Targeted Promotion and Invitation

展前和展期现场报道，会刊资料和大众媒体推介推广，通过电话、电子邮件、短信、公众号等方式进行重点客户和观众邀约，持续放大溢出带动效应。

Invite key clients and visitors in the form of pre-exhibition and exhibition live reports, conference materials and mass media promotion, telephone, e-mail, text messages, WeChat public accounts, etc. to continue to amplify the driving effect.

展品布局

LAYOUT of ENTERPRISE & BUSINESS EXHIBITION

一、热管理材料展区（Thermal Management Materials Area）

• 金属材料

原材料：铜型材，铝型材，钨、钼、铜粉末，铝热传输材料，铜网等；

导热材料：铜箔，泡沫铜，铝合金，镁合金，铜合金，钨/钼铜合金，金刚石铜/铝，石墨铜/铝，石墨烯铜/铝，铝基碳化硅等；

芯片封装：电子浆料，锡铅焊料，无铅焊料，纳米烧结银，锡膏等；

• Metal Materials

Raw Materials: copper profile, aluminum profile, tungsten, molybdenum, copper powder, aluminum heat transfer materials, copper mesh, etc.

Thermal Conductive Materials: copper foil, copper foam, aluminum alloy, magnesium alloy, copper alloy, tungsten/molybdenum-copper alloy, diamond copper/aluminum, graphite copper/aluminum, graphene copper/aluminum, aluminum-based silicon carbide (AlSiC), etc.

Chip Packaging: electronic paste, tin-lead solder, lead-free solder, nano sintered silver, solder paste, etc.

• 无机非金属材料

原材料：氧化铝，氮化铝，氮化硅，氮化硼，金刚石，碳纤维，石墨烯，二氧化硅，碳化硅，石墨，PI膜等；

导热材料：热电材料，无机相变材料，碳化硅热沉，石墨膜，石墨烯导热膜，碳纤维导热垫片，金刚石微粉，金刚石热沉，单晶金刚石等；

陶瓷基板及金属化：氧化铝基板，氮化铝基板，氮化硅基板，LTCC/HTCC陶瓷基板，DBC/AMB/DPC陶瓷基板；

隔热材料：云母绝缘材料，玻璃纤维/陶瓷纤维隔热材料，气凝胶，泡沫隔热材料，真空绝热板，碳毡，复合保温隔热材料等；

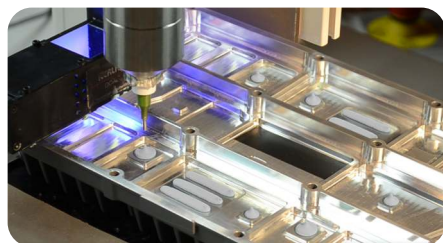
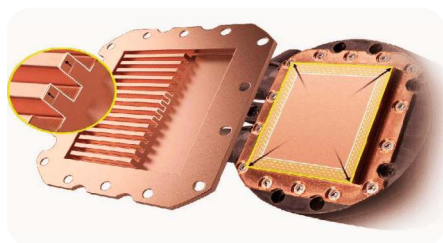
• Inorganic Non-metallic Materials

Raw Materials: alumina, aluminum nitride, silicon nitride, boron nitride, diamond, fiber, graphene, silica, silicon carbide, graphite, PI film, etc.

Thermal Conductive Materials: thermoelectric materials, inorganic phase change materials, silicon carbide heat sink, graphite film, graphene thermal conductive film, carbon fiber thermal pad, diamond micropowder, diamond heat sink, single crystal diamond, etc.

Ceramic Substrates & Metallization: alumina substrate, aluminum nitride substrate, silicon nitride substrate, LTCC/HTCC ceramic substrate, DBC/AMB/DPC ceramic substrate.

Thermal Insulation Materials: mica insulation materials, glass fiber/ceramic fiber insulation materials, aerogel, foam insulation materials, vacuum insulation panel, carbon felt, composite thermal insulation materials, etc.



展品布局

LAYOUT of ENTERPRISE & BUSINESS EXHIBITION

• 有机高分子材料

原材料: 热管工质, 清洗液, 有机硅, 聚氨酯, 环氧树脂, 丙烯酸树脂等聚合物;

热界面材料: 铜片, 导热膏, 导热硅脂, 导热凝胶, 导热垫片, 液态金属, 有机相变材料, 导热胶带, 底部填充胶, 环氧塑封料 (EMC), 封装材料等;

导热材料: 导热灌封胶, 水凝胶, 辐射制冷膜及涂料, 导热尼龙(PA), 导热聚丙烯(PP), 导热聚碳酸酯(PC), 导热聚苯硫醚(PPS), 导热液晶高分子(LCP), 导热热塑性弹性体/聚氨酯(TPE/TPU)等;

冷却液: 水基冷却液, 氟化液, 有机硅冷却液, 合成油冷却液, 生物基环保冷却液, 制冷剂, 缓蚀剂等;

• Organic Polymer Materials

Raw Materials: heat pipe working fluid, cleaning liquid, silicone, polyurethane, epoxy resin, acrylic resin and other polymers.

Thermal Interface Materials: indium sheet, thermal paste, thermal grease, thermal gel, thermal pad, liquid metal, organic phase change materials, thermal tape, underfill adhesive, epoxy molding compound (EMC), packaging materials, etc.

Thermal Conductive Materials: thermal potting adhesive, hydrogel, radiative cooling film and coating, Thermal Conductive Nylon, Thermal Conductive Polypropylene, Thermal Conductive Polycarbonate, Thermal Conductive Polyphenylene Sulfide, Thermal Conductive Liquid Crystal Polymer, Thermal Conductive TPE/TPU, etc.

Coolants: water-based coolant, fluorinated liquid, silicone-based coolant, synthetic oil coolant, bio-based eco-friendly coolant, refrigerant, corrosion inhibitor, etc.

二、热管理组件展区 (Thermal Management Components Area)

• 主动散热组件

风扇: 设计&验证, 风叶, 电机, 电路板, 组装, 检测, 调试, 包装等;

散热器: 散热片, 鳍片散热器, 针翅式散热器等;

机械泵: 液冷微泵, 压电微泵, 压电风扇, 风机, 循环泵, 离心泵, 隔膜泵等;

其它: 压缩机, 冷水机组, 精密空调, 电磁阀, 控制阀等;

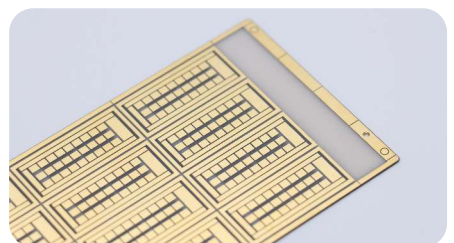
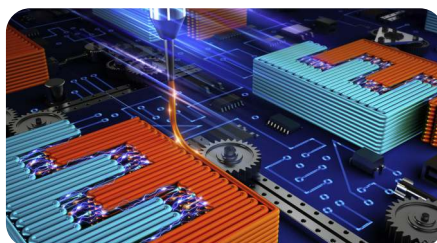
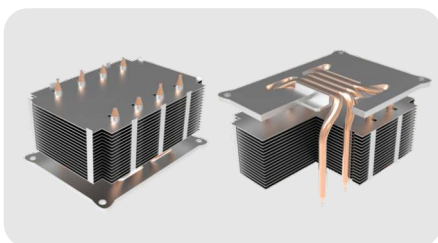
• Active Cooling Components

Fans: design & verification, blades, motors, PCB, assembly, testing, commissioning, packaging, etc.

Radiators: heat sink, fin radiator, Pin Fin Heat Sink, etc.

Mechanical Pumps: liquid cooling micro pump, piezoelectric micro pump, piezoelectric fan, blower, circulation pump, centrifugal pump, diaphragm pump, etc.

Others: compressor, chiller unit, precision air conditioner, solenoid valve, control valve, etc.



展品布局

LAYOUT of ENTERPRISE & BUSINESS EXHIBITION

• 被动散热组件

热管/VC均热板: 不锈钢, 铜粉, 铜管, 芯棒, 铜/不锈钢丝网, 蚀刻件, 工业气体; 热管, 超薄热管, 环路热管, 槽道热管, 脉动热管, 平板热管, VC均热板, 3DVC, 热管散热器, 散热模组, 工业热管等;

散热装置: 液冷板, 水冷板, 相变储能装置, 蒸发器, 冷凝器, 辐射器等;

• Passive Cooling Components

Heat Pipe/Vapor Chamber: stainless steel, copper powder, copper tube, mandrel, copper/stainless steel wire mesh, etched parts, industrial gas; heat pipe, ultrathin heat pipe, loop heat pipe, grooved heat pipe, pulsating heat pipe, flat heat pipe, vapor chamber (VC), 3DVC, heat pipe radiator, cooling module, industrial heat pipe, etc.

Cooling Devices: liquid cooling plate, water cooling plate, phase change energy storage device, evaporator, condenser, radiator, etc.

三：热管理解决方案展区 (Thermal Management Solutions Area)

• 消费电子热管理

风扇: 设计&验证, 风叶, 电机, 电路板, 组装, 检测, 调试, 包装等;

散热器: 散热片, 鳍片散热器, 针式散热器等;

热管/VC均热板: 热管, 超薄热管, 环路热管, 槽道热管, 脉动热管, 平板热管, VC均热板, 3DVC, 热管散热器, 散热模组, 工业热管等;

热设计与仿真: 热设计软件, 模拟与仿真方案, 风道设计等;

解决方案: 3D打印, 功率器件及模块, 通信, 消费电子, 工控电脑, 人工智能, 医疗设备, 智能安防, 激光, 电动车等;

创新成果: 实验室应用研究成果, 专利技术, 辐射制冷, 相变冷却等;

• Consumer Electronics Thermal Management

Fans: design & verification, blades, motors, PCB, assembly, testing, commissioning, packaging, etc.

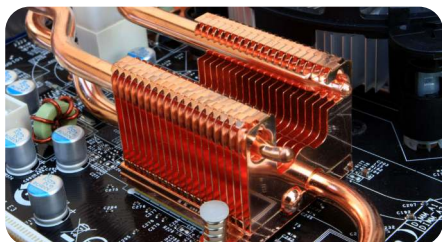
Radiators: heat sink, fin radiator, pin fin radiator, etc.

Heat Pipe/Vapor Chamber: heat pipe, ultrathin heat pipe, loop heat pipe, grooved heat pipe, pulsating heat pipe, flat heat pipe, vapor chamber (VC), 3DVC, heat pipe radiator, cooling module, industrial heat pipe, etc.

Thermal Design and Simulation: thermal design software, simulation and emulation solutions, airflow duct design, etc.

Solutions: 3D printing, power devices and modules, communications, consumer electronics, industrial computers, artificial intelligence, medical equipment, intelligent security, lasers, electric vehicles, etc.

Innovation Achievement: laboratory application research results, patent technology; radiative cooling, phase change cooling, etc.



展品布局

LAYOUT of ENTERPRISE & BUSINESS EXHIBITION

• 数据中心热管理

零部件: 快接头, 液冷管路, 分水器, 膨胀阀, 节流阀, 电磁阀, 泵, 压缩机, 蒸发器, 热交换器, 机箱, 冷量分配单元, 不间断电源, 过滤和净化装置等;

温控设备: 空调, 冷源设备, 新风系统等;

创新成果: 实验室应用研究成果, 专利技术等;

液冷技术: 单相/双相冷板式液冷, 单相/双相浸没式液冷, 喷淋式液冷, 智能温控技术等;

• Data Center Thermal Management

Components: quick disconnects, liquid cooling pipelines, manifold, expansion valves, throttle valves, solenoid valves, pumps, compressors, evaporators, heat exchangers, cabinets/chassis, cooling distribution units (CDU), uninterruptible power supplies (UPS), filtration and purification devices, etc.

Temperature Control Equipment: air conditioning, cooling source equipment, fresh air systems, etc.

Innovation Achievement: laboratory application research results, patent technology, etc.

Liquid Cooling Technology: single-phase/two-phase cold plate liquid cooling, single-phase/two-phase immersion liquid cooling, spray liquid cooling, intelligent temperature control technology, etc.

• 新能源及储能热管理

温控系统: 环保制冷剂, 液冷方案, 风冷方案, 温控技术与设备, 储能电池热管理方案, 换热器, 消防与安全等;

PCS热管理: 热流模拟, 风量风压计算, 风道布局设计, 散热片, 散热风扇, 液冷方案等;

热失控监测预警: 温度传感器, 气体传感器, 阻抗检测, 电压监测, 电池管理系统等;

动力电池: 导热灌封胶, 导热结构胶, 导热垫, 隔热材料, 保温材料, 相变材料, 液冷板, 铝热传输材料, 热仿真等;

电动车综合热管理: 冷却液, 制冷剂, 冷却油, 热泵空调, PTC, 鼓风机, 歧管模块, 阀门模块, 整车热管理方案等;

充电桩: 充电模块, 主控制器, 直流充电设备, 交流充电设备, 充电枪热管理方案等;

储热热管理: 相变材料, 储换热装置(填充床式、管壳式和板式), 装置设计, 相变储热系统方案等;

• New Energy and Energy Storage Thermal Management

Temperature Control Systems: eco-friendly refrigerants, liquid cooling solutions, air cooling solutions, temperature control technology and equipment, energy storage battery thermal management solutions, heat exchangers, fire protection and safety, etc.

PCS Thermal Management: thermal flow simulation, airflow volume and pressure calculation, air duct layout design, heat sinks, cooling fans, liquid cooling solutions, etc.

Thermal Runaway Monitoring and Early Warning: temperature sensors, gas sensors, impedance detection, voltage monitoring, battery management systems (BMS), etc.

Power Battery: thermal potting adhesive, thermal conductive structural adhesive, thermal pad, thermal insulation materials, insulation materials, phase change materials, liquid cooling plate, aluminum heat transfer materials, thermal simulation, etc.

Comprehensive EV Thermal Management: coolant, refrigerant, cooling oil, heat pump air conditioning, PTC heater, blower, manifold module, valve module, vehicle-level thermal management solutions, etc.

Charging Piles: charging modules, main controller, DC charging equipment, AC charging equipment, thermal management solutions for charging guns, etc.

Thermal Energy Storage Management: phase change materials, heat storage and exchange devices (packed bed, shell-and-tube, and plate type), device design, phase change thermal storage system solutions, etc.

展品布局

LAYOUT of ENTERPRISE & BUSINESS EXHIBITION

四：自动化设备与分析测试仪器展区

(Automation Equipment and Analytical & Testing Instruments Area)

• 自动化设备与分析测试仪器展区

生产加工：研磨，均质，分散，搅拌，脱泡，烧结，流延，灌装，分装，包装，点胶机，封装键合设备等；

陶瓷基板：烧结炉，排胶炉，钎焊炉，流延设备，研磨抛光设备，激光切割等；

液冷板：钎焊设备，铲齿设备，激光设备，3D打印设备，表面处理设备；

散热器：风扇设计，风扇加工，CNC，铲齿设备，散热器表面处理等；

石墨片/石墨烯膜：涂布/覆膜/压延/收卷，碳化/石墨化炉，模切等；

热管/VC均热板：切割，折弯，定量填粉，缩管，软缩，真空注液，激光焊接，点焊，除气，热压，压铸，高速精密冲床，表面处理，热处理，检漏，无风温箱，风洞，模组测试，生产线自动化测控，石墨模具等；

热分析仪器：差示扫描量热仪，热重分析仪，热膨胀仪，热机械分析仪，塞贝克系数测量仪，同步热分析仪，自动量热仪，热分析软件等；

物性检测仪器：黏度计，拉力机，密度计，硬度计，XRD，CT，原子力显微镜，拉曼光谱，红外光谱仪，红外热成像仪，热电偶，热敏电阻，电阻温度检测器，光纤传感器，阻抗分析仪，温度传感器，气体检测和分析，漏液检测，风扇检测调试等；

检测认证：热分析检测/认证、(高校/科研院所)测试服务平台、第三方检测机构等；

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Production and Processing: grinding, homogenization, dispersion, mixing, degassing, sintering, tape casting, filling, sub-packaging, packaging, dispensing machines, packaging and bonding equipment, etc.

Ceramic Substrate Equipment: sintering furnace, debinding furnace, brazing furnace, tape casting equipment, grinding and polishing equipment, laser cutting, etc.

Liquid Cooling Plate Equipment: brazing equipment, fin skiving equipment, laser equipment, 3D printing equipment, surface treatment equipment.

Radiator Equipment: fan design, fan processing, CNC, fin skiving equipment, radiator surface treatment, etc.

Graphite Sheet/Graphene Film Equipment: coating/laminating/calendering/winding, carbonization/graphitization furnace, die cutting, etc.

Heat Pipe/Vapor Chamber Equipment: cutting, bending, quantitative powder filling, tube necking, soft necking, vacuum liquid filling, laser welding, spot welding, degassing, hot pressing, die casting, high-speed precision punching press, surface treatment, heat treatment, leak detection, windless temperature chamber, wind tunnel, module testing, production line automation measurement and control, graphite molds, etc.

Thermal Analysis Instruments: differential scanning calorimeter (DSC), thermogravimetric analyzer (TGA), dilatometer, thermomechanical analyzer (TMA), Seebeck coefficient measurement instrument, simultaneous thermal analyzer (STA), automatic calorimeter, thermal analysis software, etc.

Physical Property Testing Instruments: viscometer, tensile testing machine, densitometer, hardness tester, XRD, CT, atomic force microscope (AFM), Raman spectrometer, infrared spectrometer, infrared thermal imager, thermocouple, thermistor, resistance temperature detector (RTD), fiber optic sensor, impedance analyzer, temperature sensor, gas detection and analysis, leak detection, fan testing and commissioning, etc.

Testing and Certification: thermal analysis testing/certification, testing service platforms (universities/research institutes), third-party testing organizations, etc.

展位价格

BOOTH RATES

展位 Booth			
展位种类 Type	规格信息 Specification	国内企业/合资企业 Domestic Enterprises/ Joint Venture Enterprises	外资企业 Foreign-Funded Enterprises
标准展位 Standard Booth	最小展位面积为：3×3=9平方米 The minimum booth: 3×3=9 m ²	15,800元/个/展期 CNY 15,800 per booth per exhibition period	3,200美元/个/展期 USD 3,200 per booth per exhibition period
	两面开放，增加10%展位附加费 Open on two sides, increasing 10% booth additional fees	17,380元/个/展期 CNY 17,380 per booth per exhibition period	3,520美元/个/展期 USD 3,520 per booth per exhibition period
室内光地 Raw Space	36平方米起租/展期 Minimum 36 m ² per exhibition period	1,480元/平方米/展期 CNY 1,480 per booth per exhibition period	320美元/平方米/展期 USD 320 per square meter per exhibition period
备注 Notes 1.展位分配遵循“先到先得”“大面积优先安排”原则，主办方将提供标准展台装修方案。 The allocation of booths will be based on the principle of "first come, first served" and "priority arrangement for large area", and the hosts will provide decoration schemes for standard booths. 2.租赁光地展位的参展企业，必须确保自行搭建的展台每个封闭面的围板高度不超过4.5米，并负责在展示区域内铺满地毯。 Exhibitors renting a blank place booth must ensure that the height of each enclosed side of their booth does not exceed 4.5 meters and that they are responsible for spreading carpets in the display area. 3.光地展位不包括任何展台搭建，也不允许相邻的展台共用围板。特装搭建方案须经过主办机构和主场搭建商的审核通过。 Indoor Blank place booths do not include any booth construction, nor are adjacent booths allowed to share hoardings. The special installation construction scheme must be approved by the hosts and the main venue builder.			

展商手册广告赞助（单位：元）				
页面 Brochure	封二 Inside Front Cover	扉页 Title Page	封三 Inside Back Cover	其它彩页 Other Pages
价格 Price (yuan)	12,000	15,000	12,000	10,000

展位价格

BOOTH RATES



标准展位示意图 Schematic of standard booth (单位/unit: mm)

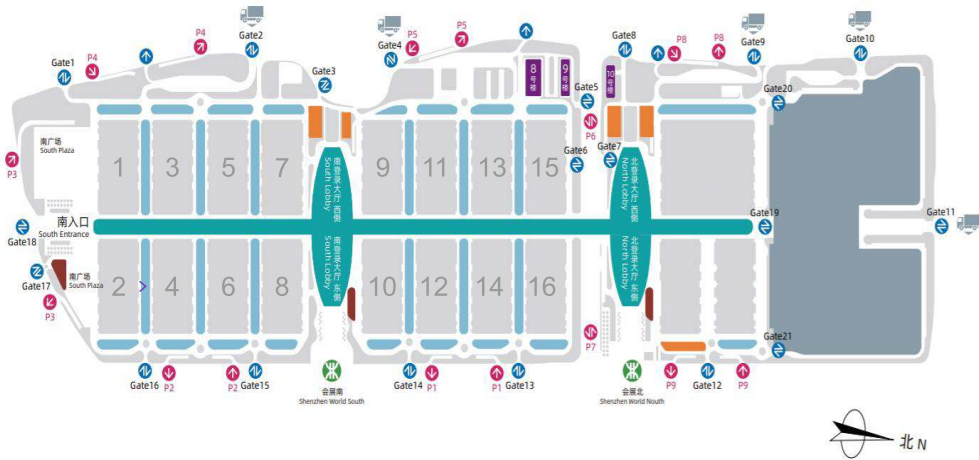
注明: 展位配置500W以内电源插座1个、9m²标准展位、垃圾桶1个、长臂射灯2只、咨询桌1张、折椅2张

说明/Descriptions

①开会前一个月将《参展商手册》传真或邮件至各参展商，含博览会的日程安排、展品运输、酒店接待、摊位搭建装饰，租用展具，增加用电等服务事项，这将协助您方便并高效地完成参展活动。其他推广渠道和呈现方式可参阅《赞助方案》。The Exhibitor Brochure will be faxed or emailed to each exhibitor one month before the exposition, including the schedule of the exposition, exhibits transportation, hotel reception, booth construction and decoration, rental of exhibition equipment, increased electricity and other service matters, which will assist you to complete the exposition activities conveniently and efficiently. Other promotion channels and presentation methods can be found in the Sponsorship Program.

②展位确认流程: 意向申请→展位确认→签订合同→费用结算→展品展示。Booth Confirmation Process: Intention application - booth confirmation - contract signing - fee settlement - exhibits display.

深圳国际会展中心（宝安）
Shenzhen World Exhibition & Convention Center



展会联系

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洞见热管理



扫码报名

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